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From: Yingsheng Tung
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-5355

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of
Miyazaki

Docket Number: TI-36833

Serial No.: 10/750/059

Art Unit: 2823

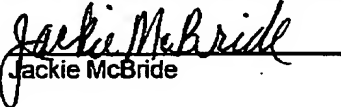
Filed: 12/30/2003

Examiner: Thao Le

For: FLIP-CHIP ON FILM ASSEMBLY FOR BALL GRID ARRAY...

CERTIFICATION OF FACSIMILE TRANSMISSION

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<input type="checkbox"/> FORMAL DRAWINGS			
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NAME OF INVENTOR(S): HIROSHI MIYAZAKI		RECEIPT DATE & SERIAL NO.: Serial No.: 10/750,059	
TITLE OF INVENTION: SOLDER BALL PAD STRUCTURE		Conf. No: 9129	
TI FILE NO.: TI-36833	DEPOSIT ACCT. NO.: 20-0668		
FAXED: 03/31/2006			
DUE: 04/14/2006			
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Texas Instruments Incorporated
PO Box 655474, M/8 3999
Dallas, TX 75265